

T-6000-L



- Best bonding performance in the market
- Designed for tomorrow's semiconductor needs
- One machine, unlimited bonding processes
- Made in Germany 

The ultimate bonding platform from prototyping to volume production.

The T-6000-L DIE Bonder combines precision with customized modularity.

Best ROI in the market.

Quick changeover between all bonding technologies.

Unique manual mode for instant DIE bonding.

Technical Data

Placement Area with Wafer
 Wafer Size
 Placement Area w/o Wafer
 Z-Movement
 Chip Rotation max.
 Bond Force Range
 Axis Speed
 Placement Accuracy
 Axis Resolution
 Min./Max. Component Size

315 mm x 400 mm
 2" – 8" (Ring & Frame)
 480 mm x 405 mm
 100 mm
 up to 360°
 10 g – up to 5.000 g *
 up to 1.8 m/sec
 8 µm @ 3 sigma
 XYZ: 0.01 µm, Theta: 0.01°
 80 µm – 100 mm **

* Higher bond force on request

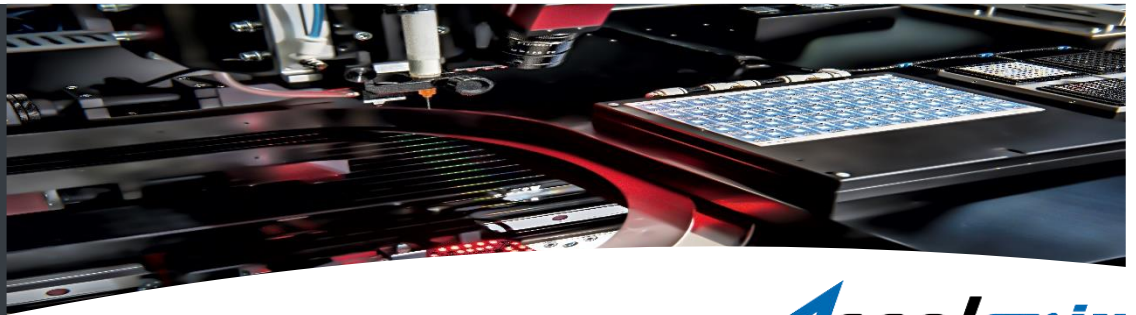
** Other dimensions on request | Note: All specifications are subject to change without notice

Contact

Tresky GmbH
 Neuendorfstrasse 19 B
 16761 Hennigsdorf
 Germany

+49 (0) 3302 86692-0
 info@tresky.de

For more information
 about our products or
 services please visit our
 website www.tresky.de



DIE Attach Technologies

- Micro Assembly
- Eutectic Bonding
- Stamping
- Ultrasonic Bonding
- Flip Chip Bonding
- Thermosonic Bonding
- Thermocompression Bonding
- Flux Dipping
- Adhesive Bonding
- DIE Stacking

Applications (Customer Specific)

- DAF Bonding
- Multi DIE Bonding
- MEMS
- SMD Bonding
- 3D Packaging (SiP)
- Laser Bar Stacking
- Glas Frit Bonding
- TO Header Bonding
- Vcsel Bonding
- RFID Assembly
- DIE Sorting

Modules & Options

- Wafer Table with DIE Ejector
- UV Indexer
- WRGB Light
- Heating Plates
 - Up to 450°C
 - Ramp rates up to 60 K/s
- Inert Gas Protection
- Automatic Tool Change
- Several Dispensing Options
- Stamping Unit
- Tool Heating
- Feeder Unit
- Uplooking Camera
- ID Scanner
- DIE Flipping Unit

Features

- Manual Mode
- Multichip Application Capability
- Post Bond Inspection
- Software integrated temp. Control
- Wafer Mapping
- OCR
- Traceability
- MES
- Automatic Dispense Needle Calibration
- Customer Specific Workspace
- Scrubbing
- Pattern Recognition Methods
- Deep Access Bonding (15mm)
- Preform Cutter

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